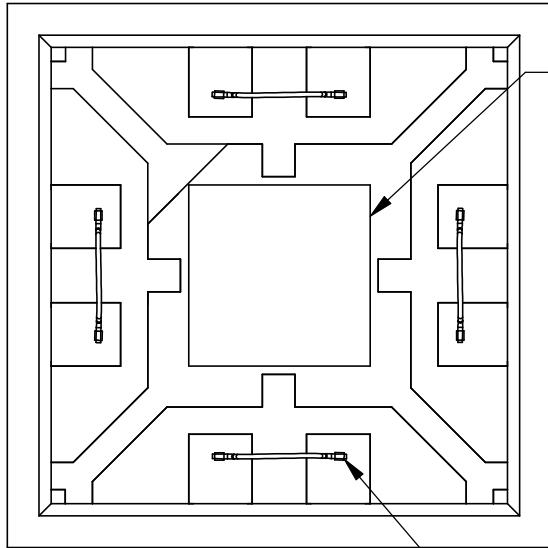


DAISY CHAIN TYPE 1
WIRE BOND TO LEAD FRAME

(STANDARD)

N 7



DUMMY DIE (Si)
WITHOUT PATTERNS

WIRE BOND DIE
TO LEAD FRAME

NET LIST:

- 1-2
- 3-4
- 5-6
- 7-N
- ETC

1
2

6
5

3 4

APPLICATION (TYPE 1):

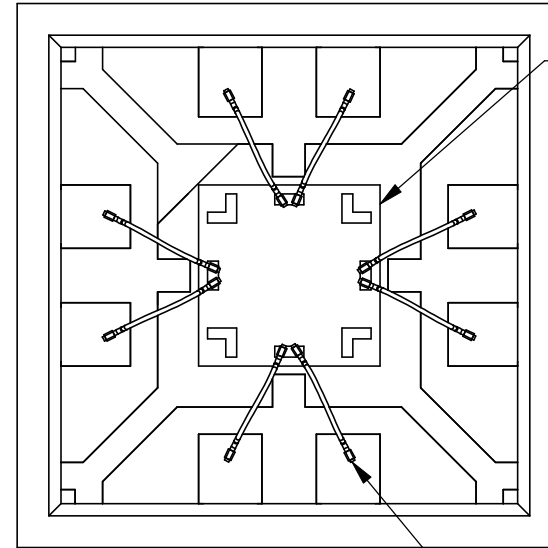
- 1) VERIFY REFLOW TEMPERATURE PROFILE.
- 2) EVALUATION OF SOLDER PASTE.
- 3) SIMULATE SMT BOARD LEVEL ASSEMBLY PROCESS.
- 4) DUMMY DIE ADDS WEIGHT AND DISTRIBUTES HEAT.
- 5) CONTINUITY TESTING.

PRICE: LOW

DAISY CHAIN TYPE 2
WIRE BOND TO DIE PADS

(SPECIAL)

N 7



DUMMY DIE (Si)
WITH PATTERNS

WIRE BOND DIE
TO LEAD FRAME

NET LIST:

- 1-2
- 3-4
- 5-6
- 7-N
- ETC

6
5

3 4

APPLICATION (TYPE 2):

- 1) EVALUATION OF SILICON INSIDE PACKAGE.
- 2) SIMULATES ELECTRICALLY FUNCTIONAL PACKAGE.
- 3) ENVIRONMENTAL PROCESS.
- 4) WIRE BOND PRACTICE.
- 5) CONTINUITY TESTING.

PRICE: HIGH

PACKAGE Notes: (Unless Otherwise Specified).

- 1) TYPES: QFN.
- 2) CONSTRUCTION: OVERMOLDED OR OPEN-CAVITY.
- 3) STANDARD DAISY CHAIN PATTERN: PIN 1-2, 3-4, 5-6, 7-N, ETC.
- 4) CUSTOMIZED DAISY CHAIN PATTERNS AVAILABLE.

TOLERANCE UNLESS NOTED		APPROVALS		DATE		TopLine [®]			
X.X	+/- 0.3	DRAWN J. Hines		2/18/2011					
X.XX	+/- 0.03	ENG				SCALE 24:1			
X.XXX	+/- 0.003	MFG							
ANGLES +/- 0.5°		QA				DRAWING NO. 150900			
ALL DIMENSIONS IN		CUST							
<input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		REVISED				DO NOT SCALE DRAWING			
THIRD ANGLE PROJECTION									